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TRANSISTORS, LOW POWER, PNP

BASED ON TYPE 2N2905A

ESCC Detail Specification No. 5202/002





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DOCUMENTATION CHANGE NOTICE

(Refer to https://escies.org for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION		
187, 1902	Specification up issued to incorporate editorial and technical changes per DC	Rs.	······
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1. <u>GENERAL</u>

1.1 <u>SCOPE</u>

This specification details the ratings, physical and electrical characteristics and test and inspection data for the component type variants and/or the range of components specified below. It supplements the requirements of, and shall be read in conjunction with, the ESCC Generic Specification listed under Applicable Documents.

1.2 <u>APPLICABLE DOCUMENTS</u>

The following documents form part of this specification and shall be read in conjunction with it:

- (a) ESCC Generic Specification No. 5000
- (b) MIL-STD-750, Test Methods and Procedures for Semiconductor Devices

1.3 <u>TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS</u> For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. 21300 shall apply.

1.4 THE ESCC COMPONENT NUMBER AND COMPONENT TYPE VARIANTS

1.4.1 <u>The ESCC Component Number</u>

The ESCC Component Number shall be constituted as follows:

Example: 520200201

- Detail Specification Reference: 5202002
- Component Type Variant Number: 01 (as required)

1.4.2 <u>Component Type Variants</u>

The component type variants applicable to this specification are as follows:

				Tierr	ninal
_	Variant Number	Based on Type	Case	Lead [®] Material and Finish	Weight max g
(hai	01	2N2905A	TO-39	D2	1.2
	02	2N2905A	TO-39	D3 or D4	1.2

The lead material and finish shall be in accordance with the requirements of ESCC Basic Specification No. 23500.

1.5 MAXIMUM RATINGS

termin

The maximum ratings shall not be exceeded at any time during use or storage. Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the ESCC Generic Specification.



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			/			
	Characteristics	Symbols	Maximum Ratings	Unit	Remarks	
	Collector-Base Voltage	V _{CBO}	-60	V	Over entire	
	Collector-Emitter Voltage	V _{CEO}	-60	V	operating temperature	
	Emitter-Base Voltage	V _{EBO}	(-5)	V	range	
	Collector Current	۱ _C	-600	mA	Continuous	
	Power Dissipation	P _{tot1}	0.6	W	At T _{amb} ≤ +25°C	(make
(see attached)		P _{tot2}	3	W	At T _{case} ≤ +25≟Ø Note-t	bigger
attached	Operating Temperature Range	T _{op}	-65 to +200	°C	Note & 1	
	Storage Temperature Range	T _{stg}	-65 to +200	°C	Note 🕱 1	
	Soldering Temperature	T _{sol}	+260	°C	Note 3 2	
Ī	IOTES:		_	5	and any handlin	

8 shall be carried out in a 100% inert atmosphere.

Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the 2.8 same lead shall not be resoldered until 3 minutes have elapsed.

PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION 1.6

Metal Can Package (TO-39) - 3 lead



Symbols	Dimensio	Notes	
Symbols	Min	Max	INUICS
Øa	4.83	5.35	
A	6	6.6	
Øb	0.4	0.533	2, 3

Thermal Resistance,				
Junction-to-Ambient	R _{th(j-a)}	291.7	°C/W	
Thermal Resistance,				
Junction-to-Case	R _{th(j-c)}	58.3	°C/W	

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NOTES:

1. The collector is internally connected to the case.

1.8 MATERIALS AND FINISHES

Materials and finishes shall be as follows:

- a) Case The case shall be hermetically sealed and have a metal body with hard glass seals.
- b) Leads/Terminals As specified in Component Type Variants.

2. <u>REQUIREMENTS</u>

2.1 <u>GENERAL</u>

The complete requirements for procurement of the components specified herein are as stated in this specification and the ESCC Generic Specification. Permitted deviations from the Generic Specification, applicable to this specification only, are listed below.

Permitted deviations from the Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESCC requirement and do not affect the component's reliability, are listed in the appendices attached to this specification.

2.1.1 <u>Deviations from the Generic Specification</u> None.

2.2 MARKING

The marking shall be in accordance with the requirements of ESCC Basic Specification No. 21700 and as follows.

The information to be marked on the component shall be:

- (a) The ESCC qualified components symbol (for ESCC qualified components only).
- (b) The ESCC Component Number.
- (c) Traceability information.

2.3 <u>TERMINAL STRENGTH</u>

The test conditions for terminal strength, tested as specified in the ESCC Generic Specification, shall be as follows:

Test Condition: E, lead fatigue.

2.4	ELECTRICAL MEASUREMENTS AT ROOM, HIGH AND LOW TEMPERATURES
	Electrical measurements shall be performed at room, high and low temperatures.



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Characteristics	Symbols	Lin	Units	
	요리가 가지가 가장 1997년 - 1997년 - 1997년 - 1997년 - 1997년 1997년 - 1997년 - 1 1997년 - 1997년 - 1997년 1997년 - 1997년 -	Min	Max	
Collector-Base Cut-off Current	I _{CBO}	-	-10	nA
Forward-Current Transfer Ratio 3	h _{FE3}	100	300	-
Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	-400	mV

2.7 HIGH TEMPERATURE REVERSE BIAS BURN-IN CONDITIONS

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	T _{amb}	+150 (+0 -5)	°C
Collector-Base Voltage	V _{CB}	50	V
Duration	t	72 minimum	Hours

2.8 POWER BURN-IN CONDITIONS

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	T _{amb}	+20 to +50	°C
Power Dissipation	P _{tot}	As per Maximum Ratings. P _{tot1} sterated at the chosen T _{amb} wing the	W
Collector-Base Voltage	V _{CB}	-40	V

2.9

The conditions shall be as specified for Power Burn-in.



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APPENDIX 'A'

AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

	ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS
	Deviations from Room Temperature Electrical Measurements	All AC characteristics (Room Temperature Electrical Measurement Note 2) may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes AC characteristic measurements per the Detail Specification.
		A summary of the pilot lot testing shall be provided if required by the Purchase Order.
	Deviations from High and Low Temperatures Electrical Measurements	All characteristics specified may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes characteristic measurements at high and low temperatures per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.
(Approved BCR 447 refers)	Deviations from Screening Tests - Charte F3	Solderability is not applicable unless specifically stopulated in the Purchase Order.